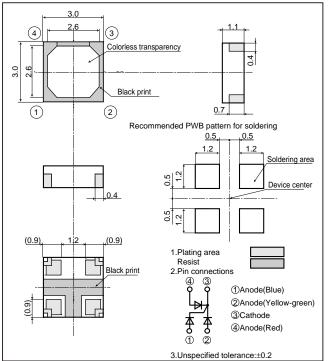
## LT1W92A(Under Development)

# 3030 Size, 1.1mm Thickness, MID\* Type Full Color Leadless Chip LED Device

#### **■** Outline Dimensions

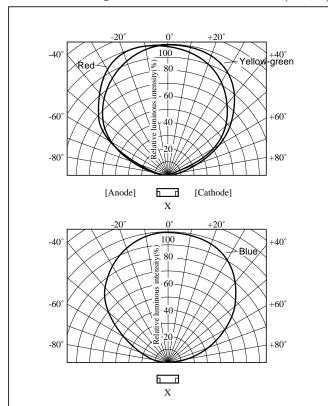




\*MID:Molded Interconnection Device

### ■ Radiation Diagram

(Ta=25°C)



Absolute Maximum Ratings

Model No.	Radiation color	Radiation material	Power dissipation Forward current IF		Peak forward current  IFM*2	Derating factor (mA/°C)		Reverse voltage V <sub>R</sub>	Operating temperature $\mathbf{T}_{\mathrm{opr}}$	Storage temperature $T_{\mathrm{stg}}$	Soldering temperature $\mathbf{T_{sol}}^{*3}$
			(mW)	(mA)	(mA)	DC	Pulse	(V)	(°C)	(°C)	(°C)
LT1W92A	Blue	GaN on SiC	200	30	100	0.67	1.33	5	-30 to +85	-40 to +100	260
	Yellow-green	GaP	84	30	50	0.40	0.67	5	-30 to +85	-40 to +100	260
	Red	GaAsP on GaP	84	30	50	0.40	0.67	5	-30 to +85	-40 to +100	260

<sup>\*1</sup> The value is specified under the condition that either color is lightened separately.

When all diodes are lightened simultaneously, the power dissipation of each diode should be less than 30% of the value specified in this table.

#### **■** Electro-optical Characteristics

(Ta=25°C)

Lens type	Model No.	Radiation color	Forward voltage V <sub>F</sub> (V)		Peak emission wavelength		Luminous intensity		Spectrum radiation bandwidth		Reverse current		Terminal capacitance		Page for
					$\lambda_p(nm)$	IF	Iv(mcd)	IF	Δλ(nm)	IF	Ir(µA)	VR	C <sub>t</sub> (pF)		characteristics
			TYP	MAX	TYP	(mA)	TYP	(mA)	TYP	(mA)	MAX	(V)	TYP	(MHz)	diagrams
Colorless transparency	LT1W92A	Blue	4.4	5.6	430	20	8.1	20	70	20	10	4	50	1	_
		Yellow-green	2.1	2.8	565	20	32.0	20	30	20	10	4	35	1	_
		Red	2.0	2.8	635	20	16.0	20	35	20	10	4	20	1	_

<sup>\*2</sup> Duty ratio=1/10, Pulse width=0.1ms

<sup>\*3</sup> For 3s or less at the temperature of hand soldering. Temperature of reflow soldering is shown on the below page.